



Appl. No. 10/735,355

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/735,355
Filing Date December 12, 2003
Inventor Zhongze Wang
Assignee Micron Technology, Inc.
Group Art Unit 2812
Examiner Jennifer M. Kennedy
Attorney's Docket No. MI22-2457
Customer No. 021567
Title: Wafer Bonding Method of Forming Silicon-on-Insulator Comprising Integrated
Circuitry

RESPONSE TO APRIL 22, 2005 OFFICE ACTION

To: Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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AMENDMENTS

Introductory Comments

In reply to the Office Action of April 22, 2005, applicant amends and remarks as follows.